

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) An automolding system comprising:
providing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.
2. (Previously presented) The automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
3. (Currently Amended) The automolding system of claim 1, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.
4. (Currently Amended) A molding system comprising:
providing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.
5. (Currently Amended) The molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

6. (Currently Amended) The molding system of claim 4, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

7. (Original) A system for molding comprising:
providing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

8. (Previously presented) The system of claim 7, wherein the laser comprises one of
an Nd:YAG laser and an excimer laser.

9. (Currently Amended) The system of claim 7, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.

Please add the following new claims:

10. (New) In an automolding system comprising:
placing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

11. (New) The automolding system of claim 10, wherein the laser comprises one of
an Nd:YAG laser and an excimer laser.

12. (New) The automolding system of claim 10, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

13. (New) In a molding system comprising:
placing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

14. (New) The molding system of claim 3, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

15. (New) The molding system of claim 3, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

16. (New) In a system for molding comprising:
placing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

17. (New) The system of claim 16, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

18. (New) The system of claim 16, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.

19. (New) In an automolding system having a cleaning apparatus comprising:
introducing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

20. (New) The automolding system of claim 19, wherein the laser comprises one of
an Nd:YAG laser and an excimer laser.

21. (New) The automolding system of claim 19, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

22. (New) A molding system having a substrate cleaning device comprising:
introducing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

23. (New) The molding system of claim 22, wherein the laser comprises one of an
Nd:YAG laser and an excimer laser.

24. (New) The molding system of claim 22, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

25. (New) A system having a cleaning device for molding comprising:
introducing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

26. (New) The system of claim 15, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

27. (New) The system of claim 15, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.

28. (New) In an automolding system comprising:
providing a substrate cleaning device for the automolding system;
introducing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using the cleaning device.

29. (New) The automolding system of claim 28, wherein the substrate cleaning device comprises a laser.

30. (New) The automolding system of claim 29, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

31. (New) The automolding system of claim 28, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

32. (New) A molding system comprising:
providing the molding system with a substrate cleaning device;
introducing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using the substrate cleaning device.

33. (New) The molding system of claim 32, wherein the substrate cleaning device comprises a laser.

34. (New) The molding system of claim 33, wherein the substrate cleaning device comprises a laser.

35. (New) The molding system of claim 32, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

36. (New) The molding system of claim 32, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

37. (New) A system for molding comprising:
providing a substrate cleaning device in the system for molding;
introducing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using the substrate cleaning device.
38. (New) The system of claim 37, wherein the substrate cleaning device comprises a laser.
39. (new) The system of claim 38, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
40. (New) The system of claim 37, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.